

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: F-0203-04 DATE: 2/27/2002 Product Affected: Plastic Ball Grid Array (PBGA) BG121	MEANS OF DISTINGUISHING CHANGED DEVICES: Product Mark Back Mark Date Code					
Date Effective: 5/27/2002	Other Alpha suffix "E" in assembly lot number					
Contact:Geoffrey CortesTitle:Manager, Corporate Quality & ReliabilityPhone #:(408) 492-8321Fax #:(408) 727-2328E-mail:gcortes@idt.com	Attachment::YesNoSamples:Availble upon request					
DESCRIPTION AND PURPOSE OF CHANGE: Die Technology Wafer Fabrication Process Assembly Process Equipment Material Testing Manufacturing Site Data Sheet Other						
RELIABILITY/QUALIFICATION SUMMARY: The qualification testing will verify that there is no change to the product reliability.						
CUSTOMER ACKNOWLEDGMENT OF RECEIPT: IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable. IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.						
Customer:	Approval for shipments prior to effective date.					
Name/Date: E-1	Mail Address:					
Title: Ph	one#/Fax#:					
CUSTOMER COMMENTS:						
IDT ACKNOWLEDGMENT OF RECEIPT:						
RECD. BY:	DATE:					



Integrated Device Technology, Inc. 2975 Stender Way, Santa Clara, CA - 95054

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ATTACHMENT - PCN #: F-0203-04

PCN Type:	To implement auto mold process
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Data Sheet Change: N/A

Detail of Change: The auto mold proces is being implemented to improve the product manufacturability by reducing the process cycle time. This change will have the following impact on the package dimension:

DESCRIPTION	FROM TO	
Mold Cap Thickness	1.17 mm	0.80 mm
Package Thickness	2.13 mm	1.81 mm

Conversion schedule (Estimated)

~	,	Sample Availability	Production Shipments
	BG121	Availble	5/3/2002

Please contact your local field sales representative for sample availability and production shipments.



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ATTACHMENT - PCN #: F-0203-04

Qualification Plan: PO

P01-03-06

Expected Completion Date:

4/26/2002

Test Vehicle: 72825LB15BG

Test Description Condition	Test Methods	Sample Size / # Fails	Test Results
Highly Accelerated Stress Test (HAST) (100 Hrs, @130°C/85%RH,Static Bias)	EIA/JESD22-A110	45/0	
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883 Method 1010	45/0	
Auto Clave (SPP) (168Hrs, @ 2ATM, 121°C)	EIA/JESD22-A102	45/0	
Package Moisture Characterization	JEDEC J-STD-20	22/0	
Internal Visual Inspection	MIL-STD-883 Method 2010	5/0	
External Visual Inspection	MIL-STD-883 Method 2009	25/0	
S.A.T	JEDEC J-STD-35	10/0	
X-ray Examination	Per IDT specification	45/0	
Bond Pull Test	MIL-STD-883 Method 2011	5/0	
Bake & Ball Shear Test	EIA/JESD22-B116	5/0	
Physical Dimension	MIL-STD-883 Method 2016	5/0	
Solder Ball Shear	JESD22-B117	3/0	
Resistance to Solvents	MIL-STD-883 Method 2015	5/0	

